



Film Capacitors

Metallized Polypropylene Film Capacitors (MKP)

Series/Type: B32669

The following products presented in this data sheet are being withdrawn.

Ordering Code	Substitute Product	Date of Withdrawal	Deadline Last Orders	Last Shipments
see following page		2014-04-11	2014-07-15	2014-10-15

For further information please contact your nearest EPCOS sales office, which will also support you in selecting a suitable substitute. The addresses of our worldwide sales network are presented at www.epcos.com/sales.

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Affected products (Ordering code)

B32669 B6105J000	B32669S3225K500
B32669B6105K000	B32669S3405K506
B32669B6155J000	B32669S3505K550
B32669B6155K000	B32669S3564K600
B32669B6205K000	B32669S3605K500
B32669B6255K000	B32669S3684K500
B32669B6305J150	B32669S3684K600
B32669B6305K000	
B32669B6405K000	
B32669B6505K000	
B32669B6605K000	
B32669C1156K000	
B32669C3106J000	
B32669C3205J000	
B32669C3205K000	
B32669C3225K000	
B32669C3255J000	
B32669C3255K000	
B32669C3305K000	
B32669C3405K000	
B32669C3605K000	
B32669C3805K000	
B32669S1104K500	
B32669S3105K500	
B32669S3105K501	
B32669S3106K500	
B32669S3126K550	
B32669S3156K550	

Not suitable for "across the line" applications!

Typical applications

- Energy storage
- Filtering

Climatic

- Max. operating temperature: 85 °C
- Climatic category (IEC 60068-1): 40/085/21

Construction

- Dielectric: polypropylene (PP)
- Cylindrical winding
- Insulating sleeve
- Face ends sealed with epoxy resin

Features

- Good self-healing properties
- RoHS-compatible

Terminals

- Axial leads, lead-free tinned
- Axial leads, insulated, tinned copper wires gathered together by a tin cover (fray), AWG 22

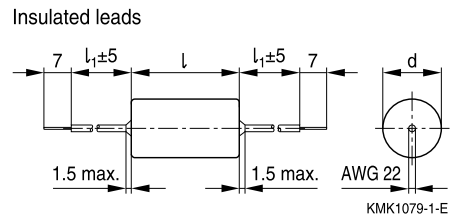
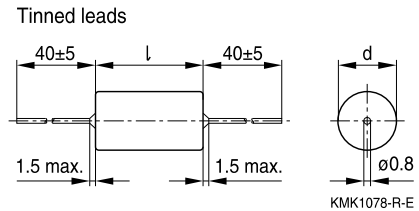
Marking

Manufacturer
 Series number
 rated capacitance (coded),
 capacitance tolerance (code letter),
 rated AC voltage, frequency, date code

Delivery mode

Bulk (untaped)

Dimensional drawing



Dimensions in mm

When bending leads, take care to leave a clearance of 1 mm to the capacitor body.



Overview of available types

Version	Tinned leads		Insulated leads	
Page	4		5	
V _{RMS} (V AC)	250	400	250	400
C _R (μF)				
1.0				
1.5				
2.0				
2.5				
3.0				
4.0				
5.0				
6.0				
8.0				
10				


B32669
AC applications (wound)
Ordering codes and packing units (tinned leads)

V_{RMS}	C_R	Max. dimensions $d \times l$ mm	Ordering code (composition see below)	Untaped pcs./MOQ
V AC	μF			
250	1.0	9.0 × 32.0	B32669C3105+000	1000
	1.5	11.0 × 32.0	B32669C3155+000	1000
	2.0	12.5 × 32.0	B32669C3205+000	800
	2.5	14.0 × 32.0	B32669C3255+000	800
	3.0	15.5 × 32.0	B32669C3305+000	600
	4.0	15.0 × 47.0	B32669C3405+000	600
	6.0	17.0 × 47.0	B32669C3605+000	400
	8.0	19.5 × 47.0	B32669C3805+000	200
400	10	21.5 × 47.0	B32669C3106+000	200
	1.0	13.0 × 32.0	B32669B6105+000	1000
	1.5	15.0 × 32.0	B32669B6155+000	800
	2.0	19.0 × 32.0	B32669B6205+000	800
	2.5	21.0 × 32.0	B32669B6255+000	600
	3.0	18.0 × 47.0	B32669B6305+000	600
	4.0	21.0 × 47.0	B32669B6405+000	400
	5.0	22.0 × 47.0	B32669B6505+000	600
6.0	25.5 × 47.0	B32669B6605+000	200	

MOQ = Minimum Order Quantity, consisting of 4 packing units.
Further E series and intermediate capacitance values on request.

Composition of ordering code

+ = Capacitance tolerance code:

K = $\pm 10\%$

J = $\pm 5\%$


Ordering codes and packing units (insulated leads)

V_{RMS}	C_R	Max. dimensions $d \times l$ mm	Ordering code (composition see below)	Untaped pcs./MOQ
V AC	μF			
250	1.0	9.0 × 32.0	B32669S3105+***	1000
	1.5	11.0 × 32.0	B32669S3155+***	1000
	2.0	12.5 × 32.0	B32669S3205+***	1000
	2.5	14.0 × 32.0	B32669S3255+***	1000
	3.0	15.5 × 32.0	B32669S3305+***	800
	4.0	15.0 × 47.0	B32669S3405+***	800
	6.0	17.0 × 47.0	B32669S3605+***	600
	8.0	19.5 × 47.0	B32669S3805+***	600
	10	21.5 × 47.0	B32669S3106+***	600
400	1.0	13.0 × 32.0	B32669S6105+***	1000
	1.5	15.0 × 32.0	B32669S6155+***	1000
	2.0	19.0 × 32.0	B32669S6205+***	1000
	2.5	21.0 × 32.0	B32669S6255+***	600
	3.0	18.0 × 47.0	B32669S6305+***	600
	4.0	21.0 × 47.0	B32669S6405+***	600
	5.0	22.0 × 47.0	B32669S6505+***	600
	6.0	25.5 × 47.0	B32669S6605+***	600

MOQ = Minimum Order Quantity, consisting of 4 packing units.
Further E series and intermediate capacitance values on request.

Composition of ordering code

+ = Capacitance tolerance code:

K = $\pm 10\%$

J = $\pm 5\%$

*** = Code number for lead version and length:

504 = Insulated leads (lead length 160 mm)

508 = Insulated leads (lead length 65 mm)


B32669
AC applications (wound)
Technical data

Operating temperature range	Max. operating temperature $T_{op,max}$	+85 °C
	Upper category temperature T_{max}	+85 °C
	Lower category temperature T_{min}	-40 °C
	Rated temperature T_R	+85 °C
Dissipation factor $\tan \delta$ at 20 °C (upper limit values)	2 · 10 ⁻³ at 1 kHz	
Time constant $\tau = C_R \cdot R_{ins}$ at 20 °C, rel. humidity ≤ 65% (minimum as-delivered values)	2500 s	
DC test voltage	$V_R = 250$ V AC: 430 V DC, 1 s $V_R = 400$ V AC: 700 V DC, 1 s	
AC test voltage	$V_R = 250$ V AC: 440 V AC, 1 s $V_R = 400$ V AC: 700 V AC, 1 s	
Damp heat test Limit values after damp heat test	21 days/40 °C/93% relative humidity Capacitance change $ \Delta C/C $ ≤ 3% Dissipation factor change $\Delta \tan \delta$ ≤ 0.5 · 10 ⁻³ (at 1 kHz) ≤ 1.0 · 10 ⁻³ (at 10 kHz) Time constant $\tau = C_R \cdot R_{ins}$ ≥ 50% of minimum as-delivered values	
Pulse handling capability (rate of voltage rise V_{pp}/τ)	≤ 10 V/μs	

Permissible AC voltage V_{RMS} versus frequency f

Values can be obtained on request. In specific cases please provide a scaled voltage/ time graph and state operating conditions.



Mounting guidelines

1 Soldering

1.1 Solderability of leads

The solderability of terminal leads is tested to IEC 60068-2-20, test Ta, method 1.

Before a solderability test is carried out, terminals are subjected to accelerated ageing (to IEC 60068-2-2, test Ba: 4 h exposure to dry heat at 155 °C). Since the ageing temperature is far higher than the upper category temperature of the capacitors, the terminal wires should be cut off from the capacitor before the ageing procedure to prevent the solderability being impaired by the products of any capacitor decomposition that might occur.

Solder bath temperature	235 ±5 °C
Soldering time	2.0 ±0.5 s
Immersion depth	2.0 +0/-0.5 mm from capacitor body or seating plane
Evaluation criteria: Visual inspection	Wetting of wire surface by new solder ≥90%, free-flowing solder

1.2 Resistance to soldering heat

Resistance to soldering heat is tested to IEC 60068-2-20, test Tb, method 1A.

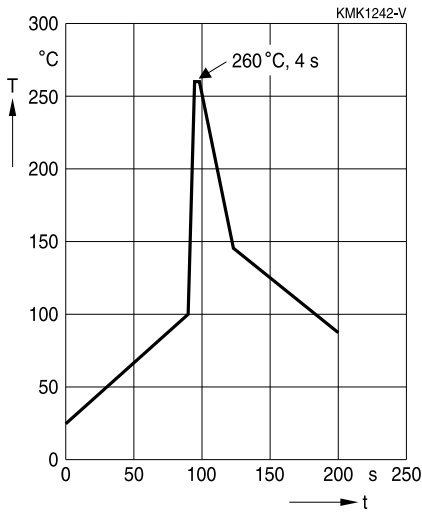
Conditions:

Series	Solder bath temperature	Soldering time
MKT boxed (except 2.5 × 6.5 × 7.2 mm) coated uncoated (lead spacing > 10 mm)	260 ±5 °C	10 ±1 s
MFP MKP (lead spacing > 7.5 mm)		
MKT boxed (case 2.5 × 6.5 × 7.2 mm)		5 ±1 s
MKP (lead spacing ≤ 7.5 mm) MKT uncoated (lead spacing ≤ 10 mm) insulated (B32559)		< 4 s recommended soldering profile for MKT uncoated (lead spacing ≤ 10 mm) and insulated (B32559)



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AC applications (wound)



Immersion depth	2.0 +0/−0.5 mm from capacitor body or seating plane
Shield	Heat-absorbing board, (1.5 ±0.5) mm thick, between capacitor body and liquid solder
Evaluation criteria:	
Visual inspection	No visible damage
$\Delta C/C_0$	2% for MKT/MKP/MFP 5% for EMI suppression capacitors
$\tan \delta$	As specified in sectional specification



1.3 General notes on soldering

Permissible heat exposure loads on film capacitors are primarily characterized by the upper category temperature T_{max} . Long exposure to temperatures above this type-related temperature limit can lead to changes in the plastic dielectric and thus change irreversibly a capacitor's electrical characteristics. For short exposures (as in practical soldering processes) the heat load (and thus the possible effects on a capacitor) will also depend on other factors like:

- Pre-heating temperature and time
- Forced cooling immediately after soldering
- Terminal characteristics:
 - diameter, length, thermal resistance, special configurations (e.g. crimping)
- Height of capacitor above solder bath
- Shadowing by neighboring components
- Additional heating due to heat dissipation by neighboring components
- Use of solder-resist coatings

The overheating associated with some of these factors can usually be reduced by suitable countermeasures. For example, if a pre-heating step cannot be avoided, an additional or reinforced cooling process may possibly have to be included.

EPCOS recommends the following conditions:

- Pre-heating with a maximum temperature of 110 °C
- Temperature inside the capacitor should not exceed the following limits:
 - MKP/MFP 110 °C
 - MKT 160 °C
- When SMD components are used together with leaded ones, the leaded film capacitors should not pass into the SMD adhesive curing oven. The leaded components should be assembled after the SMD curing step.
- Leaded film capacitors are not suitable for reflow soldering.

Uncoated capacitors

For uncoated MKT capacitors with lead spacings ≤ 10 mm (B32560/B32561) the following measures are recommended:

- pre-heating to not more than 110 °C in the preheater phase
- rapid cooling after soldering



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AC applications (wound)

Cautions and warnings

- Do not exceed the upper category temperature (UCT).
- Do not apply any mechanical stress to the capacitor terminals.
- Avoid any compressive, tensile or flexural stress.
- Do not move the capacitor after it has been soldered to the PC board.
- Do not pick up the PC board by the soldered capacitor.
- Do not place the capacitor on a PC board whose PTH hole spacing differs from the specified lead spacing.
- Do not exceed the specified time or temperature limits during soldering.
- Avoid external energy inputs, such as fire or electricity.
- Avoid overload of the capacitors.

The table below summarizes the safety instructions that must always be observed. A detailed description can be found in the relevant sections of the chapters "General technical information" and "Mounting guidelines".

Topic	Safety information	Reference chapter "General technical information"
Storage conditions	Make sure that capacitors are stored within the specified range of time, temperature and humidity conditions.	4.5 "Storage conditions"
Flammability	Avoid external energy, such as fire or electricity (passive flammability), avoid overload of the capacitors (active flammability) and consider the flammability of materials.	5.3 "Flammability"
Resistance to vibration	Do not exceed the tested ability to withstand vibration. The capacitors are tested to IEC 60068-2-6. EPCOS offers film capacitors specially designed for operation under more severe vibration regimes such as those found in automotive applications. Consult our catalog "Film Capacitors for Automotive Electronics".	5.2 "Resistance to vibration"



Topic	Safety information	Reference chapter "Mounting guidelines"
Soldering	Do not exceed the specified time or temperature limits during soldering.	1 "Soldering"
Cleaning	Use only suitable solvents for cleaning capacitors.	2 "Cleaning"
Embedding of capacitors in finished assemblies	When embedding finished circuit assemblies in plastic resins, chemical and thermal influences must be taken into account. Caution: Consult us first, if you also wish to embed other uncoated component types!	3 "Embedding of capacitors in finished assemblies"



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AC applications (wound)

Symbols and terms

Symbol	English	German
α	Heat transfer coefficient	Wärmeübergangszahl
α_C	Temperature coefficient of capacitance	Temperaturkoeffizient der Kapazität
A	Capacitor surface area	Kondensatoroberfläche
β_C	Humidity coefficient of capacitance	Feuchtekoeffizient der Kapazität
C	Capacitance	Kapazität
C_R	Rated capacitance	Nennkapazität
ΔC	Absolute capacitance change	Absolute Kapazitätsänderung
$\Delta C/C$	Relative capacitance change (relative deviation of actual value)	Relative Kapazitätsänderung (relative Abweichung vom Ist-Wert)
$\Delta C/C_R$	Capacitance tolerance (relative deviation from rated capacitance)	Kapazitätstoleranz (relative Abweichung vom Nennwert)
dt	Time differential	Differentielle Zeit
Δt	Time interval	Zeitintervall
ΔT	Absolute temperature change (self-heating)	Absolute Temperaturänderung (Selbsterwärmung)
$\Delta \tan \delta$	Absolute change of dissipation factor	Absolute Änderung des Verlustfaktors
ΔV	Absolute voltage change	Absolute Spannungsänderung
dV/dt	Time differential of voltage function (rate of voltage rise)	Differentielle Spannungsänderung (Spannungsflankensteilheit)
$\Delta V/\Delta t$	Voltage change per time interval	Spannungsänderung pro Zeitintervall
E	Activation energy for diffusion	Aktivierungsenergie zur Diffusion
ESL	Self-inductance	Eigeninduktivität
ESR	Equivalent series resistance	Ersatz-Serienwiderstand
f	Frequency	Frequenz
f_1	Frequency limit for reducing permissible AC voltage due to thermal limits	Grenzfrequenz für thermisch bedingte Reduzierung der zulässigen Wechselspannung
f_2	Frequency limit for reducing permissible AC voltage due to current limit	Grenzfrequenz für strombedingte Reduzierung der zulässigen Wechselspannung
f_r	Resonant frequency	Resonanzfrequenz
F_D	Thermal acceleration factor for diffusion	Therm. Beschleunigungsfaktor zur Diffusion
F_T	Derating factor	Deratingfaktor
i	Current (peak)	Stromspitze
I_C	Category current (max. continuous current)	Kategoriestrom (max. Dauerstrom)



Symbol	English	German
I_{RMS}	(Sinusoidal) alternating current, root-mean-square value	(Sinusförmiger) Wechselstrom
i_z	Capacitance drift	Inkonstanz der Kapazität
k_0	Pulse characteristic	Impuls Kennwert
L_S	Series inductance	Serieninduktivität
λ	Failure rate	Ausfallrate
λ_0	Constant failure rate during useful service life	Konstante Ausfallrate in der Nutzungsphase
λ_{test}	Failure rate, determined by tests	Experimentell ermittelte Ausfallrate
P_{diss}	Dissipated power	Abgegebene Verlustleistung
P_{gen}	Generated power	Erzeugte Verlustleistung
Q	Heat energy	Wärmeenergie
ρ	Density of water vapor in air	Dichte von Wasserdampf in Luft
R	Universal molar constant for gases	Allg. Molarkonstante für Gas
R	Ohmic resistance of discharge circuit	Ohmscher Widerstand des Entladekreises
R_i	Internal resistance	Innenwiderstand
R_{ins}	Insulation resistance	Isolationswiderstand
R_P	Parallel resistance	Parallelwiderstand
R_S	Series resistance	Serienwiderstand
S	severity (humidity test)	Schärfegrad (Feuchtest)
t	Time	Zeit
T	Temperature	Temperatur
τ	Time constant	Zeitkonstante
$\tan \delta$	Dissipation factor	Verlustfaktor
$\tan \delta_D$	Dielectric component of dissipation factor	Dielektrischer Anteil des Verlustfaktors
$\tan \delta_P$	Parallel component of dissipation factor	Parallelanteil des Verlustfaktors
$\tan \delta_S$	Series component of dissipation factor	Serienanteil des Verlustfaktors
T_A	Ambient temperature	Umgebungstemperatur
T_{max}	Upper category temperature	Obere Kategorietemperatur
T_{min}	Lower category temperature	Untere Kategorietemperatur
t_{OL}	Operating life at operating temperature and voltage	Betriebszeit bei Betriebstemperatur und -spannung
T_{op}	Operating temperature	Betriebstemperatur
T_R	Rated temperature	Nenntemperatur
T_{ref}	Reference temperature	Referenztemperatur
t_{SL}	Reference service life	Referenz-Lebensdauer
V_{AC}	AC voltage	Wechselspannung


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AC applications (wound)

Symbol	English	German
V_C	Category voltage	Kategoriespannung
$V_{C,RMS}$	Category AC voltage	(Sinusförmige) Kategorie-Wechselspannung
V_{CD}	Corona-discharge onset voltage	Teilentlade-Einsatzspannung
V_{ch}	Charging voltage	Ladespannung
V_{DC}	DC voltage	Gleichspannung
V_{FB}	Fly-back capacitor voltage	Spannung (Flyback)
V_i	Input voltage	Eingangsspannung
V_o	Output voltage	Ausgangssspannung
V_{op}	Operating voltage	Betriebssspannung
V_p	Peak pulse voltage	Impuls-Spitzenspannung
V_{pp}	Peak-to-peak voltage Impedance	Spannungshub
V_R	Rated voltage	Nennspannung
\hat{V}_R	Amplitude of rated AC voltage	Amplitude der Nenn-Wechselspannung
V_{RMS}	(Sinusoidal) alternating voltage, root-mean-square value	(Sinusförmige) Wechselspannung
V_{SC}	S-correction voltage	Spannung bei Anwendung "S-correction"
V_{sn}	Snubber capacitor voltage	Spannung bei Anwendung "Beschaltung"
Z	Impedance	Scheinwiderstand
e	Lead spacing	Rastermaß

Important notes

The following applies to all products named in this publication:



1. Some parts of this publication contain **statements about the suitability of our products for certain areas of application**. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out **that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application**. As a rule we are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether a product with the properties described in the product specification is suitable for use in a particular customer application.
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Release 2018-10

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